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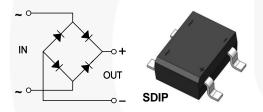


June 2015

# DF005S2 - DF10S2 Bridge Rectifier

### **Features**

- Maximum Surge Rating:  $I_{FSM} = 85 \text{ A}$  $I^2t = 30 \text{ A}^2\text{Sec}$
- Optimized V<sub>F</sub>: Typical 0.93 V at 2 A, 25°C
- DF10S Socket Compatible
- · Glass Passivated Junctions
- Lead Free Compliant to EU RoHS 2002/95/EU Directives
- Green Molding Compound: IEC61249
- · Qualified with IR Reflow and Wave Soldering



## Description

With the ever-pressing need to improve power supply efficiency, improve surge rating, improve reliability, and reduce size, the DFxS2 family sets a new standard in performance.

The new design offers an improved surge rating of 85 A. This is especially important when striving to improve reliability and increase efficiency. High efficiency designs strive to reduce circuit resistance, which, unfortunately can result in increased inrush surge. As such higher surge current ratings can be required to maintain or improve reliability.

The design also offers improved efficiency by achieving a 2 A  $V_F$  of 1.1 V maximum at 25°C. This lower  $V_F$  also supports cooler and more efficient operation.

Finally, the DFxS2 achieves all this in a SDIP surface mount form factor, reducing board space and volumetric requirements vs. competitive devices.

# **Ordering Information**

Part Number	Top Mark	Package	Packing Method	
DF005S2	DF005S2	SDIP 4L	Tape and Reel	
DF01S2	DF01S2	O1S2 SDIP 4L Ta		
DF02S2	DF02S2	SDIP 4L Tape and Re		
DF04S2	DF04S2	SDIP 4L Tape and Reel		
DF06S2	DF06S2	SDIP 4L	Tape and Reel	
DF08S2	DF08S2	SDIP 4L	L Tape and Reel	
DF10S2	DF10S2	SDIP 4L Tape and F		

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Value						Unit	
		DF005S2	DF01S2	DF02S2	DF04S2	DF06S2	DF08S2	DF10S2	
V <sub>RRM</sub>	Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V
V <sub>DC</sub>	Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	٧
I <sub>F(AV)</sub>	Maximum Average Forward Current T <sub>A</sub> = 40°C				2.0				Α
I <sub>FSM</sub>	Peak Forward Surge Current 8.3 ms Single Half-Sine Wave Superimposed on Rated Load(JEDEC Method)				85				А
T <sub>STG</sub>	Storage Temperature Range				55 to +150	)			°C
T <sub>J</sub>	Operating Junction Temperature Range				55 to +150	)			°C

### Thermal Characteristics(1)

Symbol	Parameter	Conditions	Max.	Unit
		Single-Die Measurement (Maximum Land Pattern: 13 x 13 mm)	60	
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	Multi-Die Measurement (Maximum Land Pattern: 13 x 13 mm)	50	°C/W
		Multi-Die Measurement (Minimum Land Pattern: 1.3 x 1.5 mm)	100	
ΨJL	Thermal Characterization Parameter, Junction to Lead	Single-Die Measurement (Maximum and Minimum Land Pattern)	25	°C/W

### Note:

1. The thermal resistances ( $R_{\theta JA} \& \psi_{JL}$ ) are characterized with the device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm.

Heating effect from adjacent dice is considered and only two dices are powered at the same time.

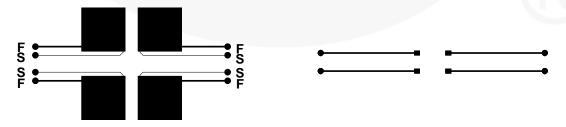


Figure 1. Maximum Pads of 2 oz Copper

Figure 2. Minimum Pads of 2 oz Copper

# **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V <sub>F</sub>	Forward Voltage Drop per Bridge Element	I <sub>F</sub> = 2.0 A			1.1	V
I - I -	DC Reverse Current at Rated DC Blocking Voltage	$T_J = 25^{\circ}C$			3	μА
		T <sub>J</sub> = 125°C			500	
l <sup>2</sup> t	Rating for Fusing (t < 8.3 ms)				30	A <sup>2</sup> S
CJ	Junction Capacitance	V <sub>R</sub> = 4.0 V, f = 1.0 MHz		23		pF

# **Typical Performance Characteristics**

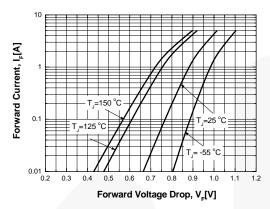


Figure 3. Typical Instantaneous Forward Characteristics

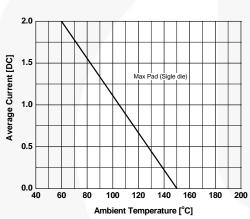


Figure 5. Maximum Average Current vs.
Ambient Temperature

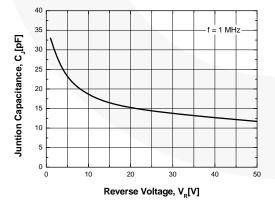


Figure 7. Typical Junction Capacitance

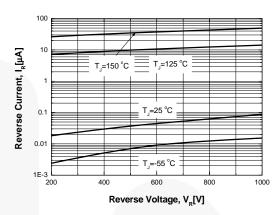


Figure 4. Typical Reverse Characteristics

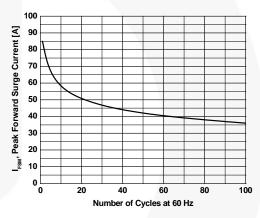


Figure 6. Peak Forward Surge Current vs.

Number of Cycles at 60Hz

# **Physical Dimensions** 5.200 5.000 ( 1.30 ) ( 1.50 ) 3 PIN1 ID **OPTIONAL** 6.500 10.300 6.200 9.400 10,40 1.200 0.890 - ( 5.10 ) -**TOP VIEW** LAND PATTERN RECOMMENDATION 8.510 7.874 CHAMFER OPTIONAL 8.050 7.370 2.60 0.330 2.20 0.220 0.330 1.530\_ 0.076 (1.12) 1.020 SIDE VIEW **END VIEW** NOTES: A. THIS PACKAGE DOES NOT CONFORM TO ANY REFERENCE STANDARD. B. ALL DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS. G. DRAWING FILE NAME: MKT-SDIP04AREV5. Figure 8. 4-LEAD, SDIP, 6.5 MM WIDE





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